

# Bill of Materials

TI DESIGNS  
TIDA-00113

Item Number	Part Reference	Description	Distributor	Distributor Part Number	Manufactured by	Part Number	Value	Quantity	PCB Footprint
1	C1-C61	CAP CERM .1UF 10% 10V	Digikey	478-1129-1-ND	AVX Corporation	0402ZD104KAT2A	100n	61	RESCAP-
2	C62-C66	CAP TANT 22UF 10V 20% 1206	Digikey	478-5798-1-ND	AVX Corporation	TAJA226M010RNJ	22uF	5	CAP-002-3216
3	C67-C70	CAP 4700PF 25V CERAMIC 0402 SMD	Digikey	PCC472BQCT-ND	Panasonic - ECG	ECJ-0EB1E472K	4.7nF	4	c0402_no ss
4	C71	CAP CER 10PF 50V NP0 RF 0402	Digikey	478-5991-1-ND	AVX Corporation	04025U100CAT2A	Capacitor 0402 10pF	1	c0402_no ss
5	CAL0,CALDLY0,DCLK_RST+0,DCLK_RST-0,DDR_PH0,DES0,CEB0,FSR0,ONE-TO-ONE0,PDIO,PDQ0,SC ANTEST0,TEST_A0,TEST_B0,TPN0,VTEST+0,VTEST-0	CONN HEADER VERT SGL 3POS GOLD	Digikey	3M9448-ND	3M	961103-6404-AR	HEADER 3	17	PLUG-003-SIL-XXX-02_54
6	CALFAIL0,CALRUN0,REFCLKIN0,REFCLKOUT1,REFCLKOUT2,SCLK0,SCSB0,SDATA-READ0,SDATA-WRITE0,TDIODE0,VBG0,VCMO0,VNEGIO,VNEGQ0	CONN HEADER VERT SGL 2POS GOLD	Digikey	3M9447-ND	3M	961102-6404-AR	HEADER 2	14	PLUG-002-SIL-XXX-02_54
7	J1,J5,J6,J15-J18	CONN SMA JACK END LAUNCH PCB	Digikey	J629-ND	Emerson Network Power Connectivity Solutions	142-0711-821	sma-3	7	SOCKET-003-SMA-SAM-JPHSTE M1
8	J7,J9,J11,J13	No Populate	No Populate	No Populate	No Populate	No Populate	No Populate	4	E5387A_PROBE
9	J8,J10,J12,J14	SOCKET DOUBLE ROW .5MM 100PIN	SAMTEC	ASP-65067-01	SAMTEC	ASP-65067-01	Samtec ASP-65067-01	4	SOCKET-100-SAM-ASP-65067-01
10	P1-P4	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead & Standoff, Hex, 0.5"L #4-40 Nylon	Digikey	H542-ND & 1902CK-ND	B&F Fastener Supply & Keystone	NY PMS 440 0025 PH & 1902C	PIN SOCKET SIL	4	
11	R1-R15	RES 1.00K OHM 1/10W 1% 0603 SMD	Digikey	P1.00KHCT-ND	Panasonic - ECG	ERJ-3EKF1001V	1k	15	RESCAP-002-0603

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